PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:	Francis Bourrieres, Clement Kaiser	
Application No.:	09/830253	
Filed:	April 24, 2001	RECEIVED
For:	Method For Making Electronic Modules With Ball Connector Or With Integrated Preforms Capable of Being Soldered On A Printed Circuit And Implementing Device	AV 2 8 2003
Examiner:	Minh Trinh	ROUP 3700
Group Art Unit:	3729	

Commissioner for Patents Washington, D.C. 20231

Docket No.: N48.2-9735-US01

DATE: January 24, 2003

FACSIMILE TRANSMITTAL LETTER

TO: Examiner Trinb

FACSIMILE NO.: 703-872-9302

GROUP ART UNIT:

application.

TOTAL NUMBER OF PAGES (including cover letter):

Following please find a Second Preliminary Amendment for the above-identified

If a fee is required, Commissioner of Patents is hereby authorized to charge Deposit Account No. 22-0350 for any required fees.

Respectfully Submitted,

VÍDAS, ARRETT & STEINKRAUS,

Date: January 24, 2003

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Box ____

Assistant Commissioner for Patents

Washington, D.C. 20231

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Second Preliminary Amendment

Prior to examination, please amend the application as follows:

In The Claims:

Please amend the claims as follows:

1) (Amended twice) Method for producing an electronic module in the shape of a ball housing combining a network of balls (7) or geometrically identical preform connectors or shield system and surface-mounted components (2) on the same side of a substrate (1), thus making this module directly connectable to a printed circuit (3), wherein

soldering cream (8) is deposited simultaneously for the components and the connecting ball or shield system located on the same surface;

said components are transferred onto the corresponding mounting lands;

the ball connectors are transferred collectively onto the lands of the same side intended for them by an appropriate device; and

a single re-melting cycle permits simultaneous soldering of the components and the connecting balls or shields onto the substrate.

